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Erratum to: Constitutive Behavior of Mixed Sn-Pb/Sn-3.0Ag-0.5Cu Solder Alloys

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In Table VI of the original article the values for the ξ column were incorrect. The updated Table VI below lists the corrected values for ξ. The correct values of the model constants were used for the Anand model predictions in Figs. 11–13 and 16 presented in the original article.

Table VI. Anand model constants for Sn-3.0Ag-0.5Cu (from Ref. 3) and Sn-2.9Ag-0.5Cu-1.0Pb, Sn-2.6Ag-0.4Cu-5.0Pb, and Sn-1.4Ag-0.2Cu-20.0Pb solder alloys

	s_0 (MPa)	Q/R (K)	A (s^{-1})	ξ	m	h_0 (MPa)	$\hat{s}$ (MPa)	n	a
Sn-3.0Ag-0.5Cu	2.15	10,000	18.0	0.35	0.15	1500	2.5	0.028	1.7
Sn-2.9Ag-0.5Cu-1.0Pb	0.21	9900	17.0	0.88	0.30	1300	2.5	0.041	1.9
Sn-2.6Ag-0.4Cu-5.0Pb	0.20	9500	10.5	0.90	0.31	850	2.5	0.044	2.0
Sn-1.4Ag-0.2Cu-20.0Pb	0.19	8500	6.0	1.0	0.37	700	2.5	0.050	2.1

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